

VERIFICATION METHOD FOR DEVICE CHIPS

ABSTRACT

A verification method for device chips, includes a providing step of providing a wafer having a front surface with a plurality of devices formed thereon and demarcated by streets, the devices including non-defective devices and defective devices that are distinguished from each other based on an electrical characteristic, a dividing step of dividing the wafer into individual device chips along the streets, a defective device chip extracting step of extracting defective device chips from the individual device chips, the defective device chips corresponding to the defective devices and being defective in the electrical characteristic, and a verification step of verifying a physical characteristic of each of the extracted defective device chips.

[FIG. 3]